FAIRCHILD SEMICONDUCTOR®

May 2007

74VHC595
8-Bit Shift Register with Output Latches

Features

- High Speed: t_{PD} = 5.4ns (Typ.) at V_{CC} = 5V
- Low power dissipation: I_{CC} = 4μA (Max.) at T_A = 25°C
- High noise immunity: $V_{NIH} = V_{NIL}$ = 28% V_{CC} (Min.)
- Power down protection is provided on all inputs
- Low noise: V_{OLP} = 0.9V (Typ.)
- Pin and function compatible with 74HC595

General Description

The VHC595 is an advanced high-speed CMOS Shift Register fabricated with silicon gate CMOS technology. It achieves the high-speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

This device contains an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. The storage register has eight 3-STATE outputs. Separate clocks are provided for both the shift register and the storage register. The shift register has a direct-overriding clear, serial input, and serial output (standard) pins for cascading. Both the shift register and storage register use positive-edge triggered clocks. If both clocks are connected together, the shift register state will always be one clock pulse ahead of the storage register.

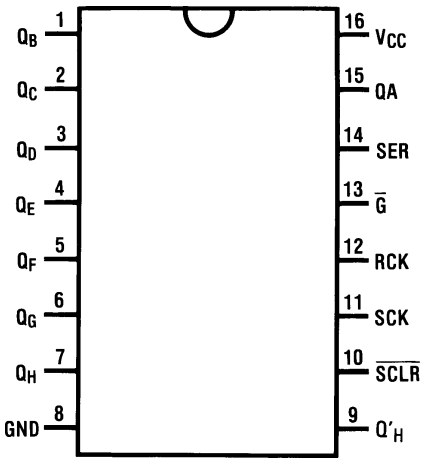
An input protection circuit insures that 0V to 7V can be applied to the input pins without regard to the supply voltage. This device can be used to interface 5V to 3V systems and two supply systems such as battery backup. This circuit prevents device destruction due to mismatched supply and input voltages.

Ordering Information

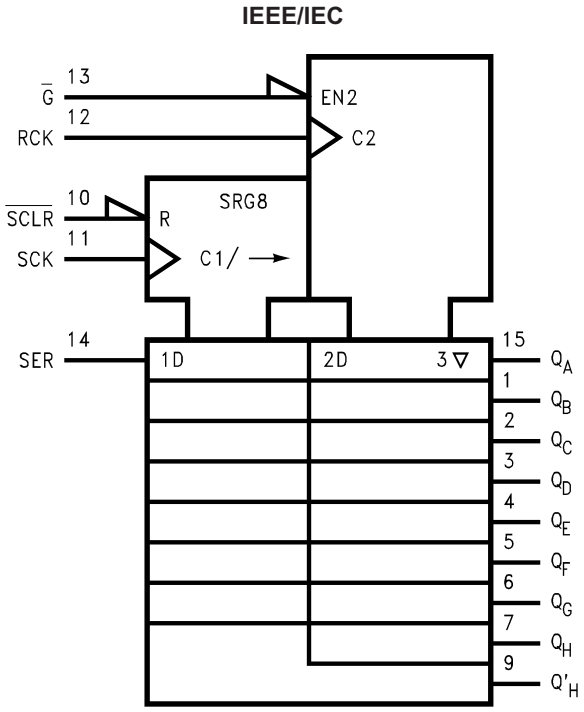
Order Number	Package Number	Package Description
74VHC595M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74VHC595SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74VHC595MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter “X” to the ordering number.

Connection Diagram



Logic Symbol



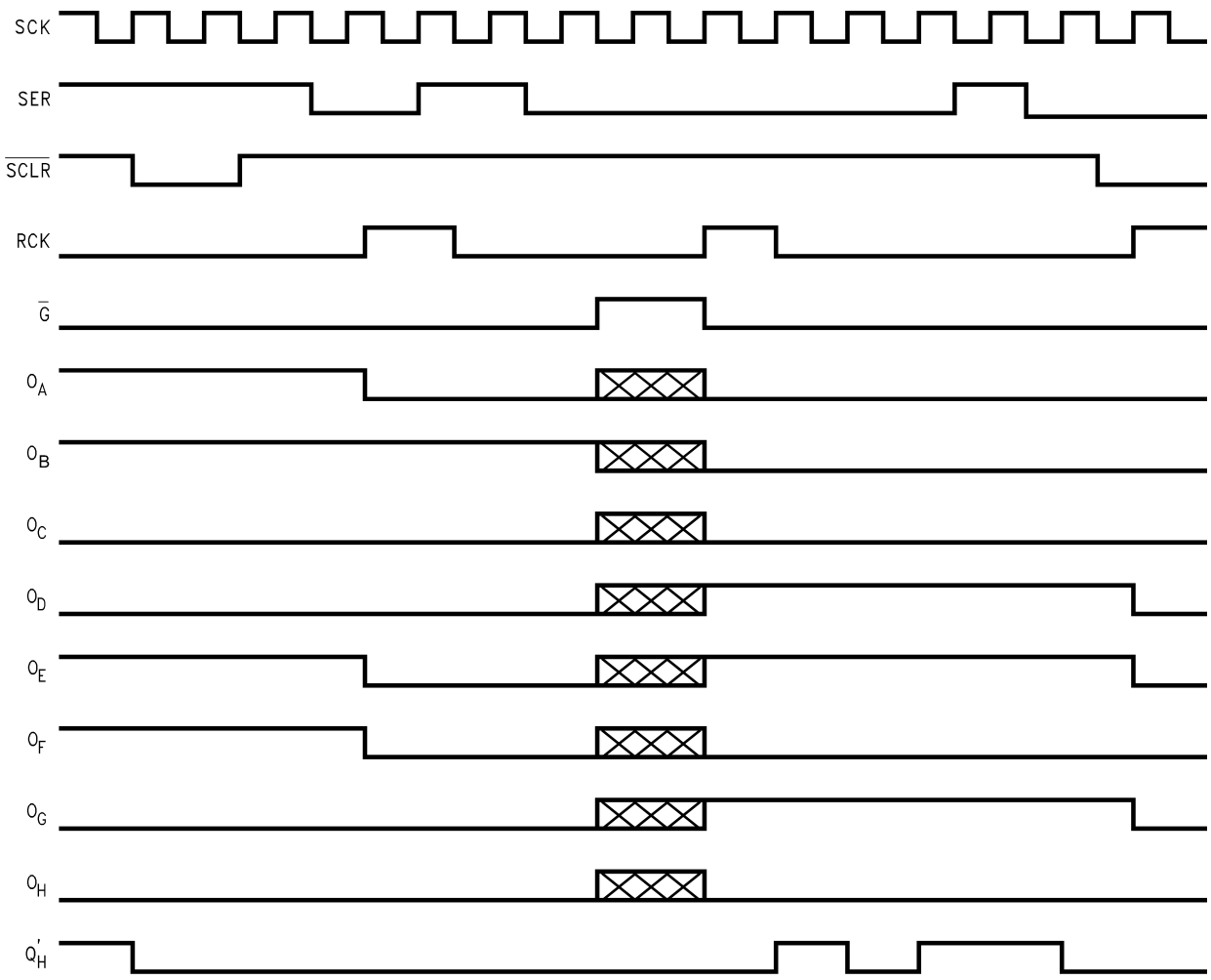
Pin Description

Pin Names	Description
SER	Serial Data Input
SCK	Shift Register Clock Input (Active rising edge)
RCK	Storage Register Clock Input (Active rising edge)
$\overline{SCLR}$	Reset Input
$\overline{G}$	3-STATE Output Enable Input (Active LOW)
$Q_A - Q_H$	Parallel Data Outputs
Q'_H	Serial Data Output

Truth Table

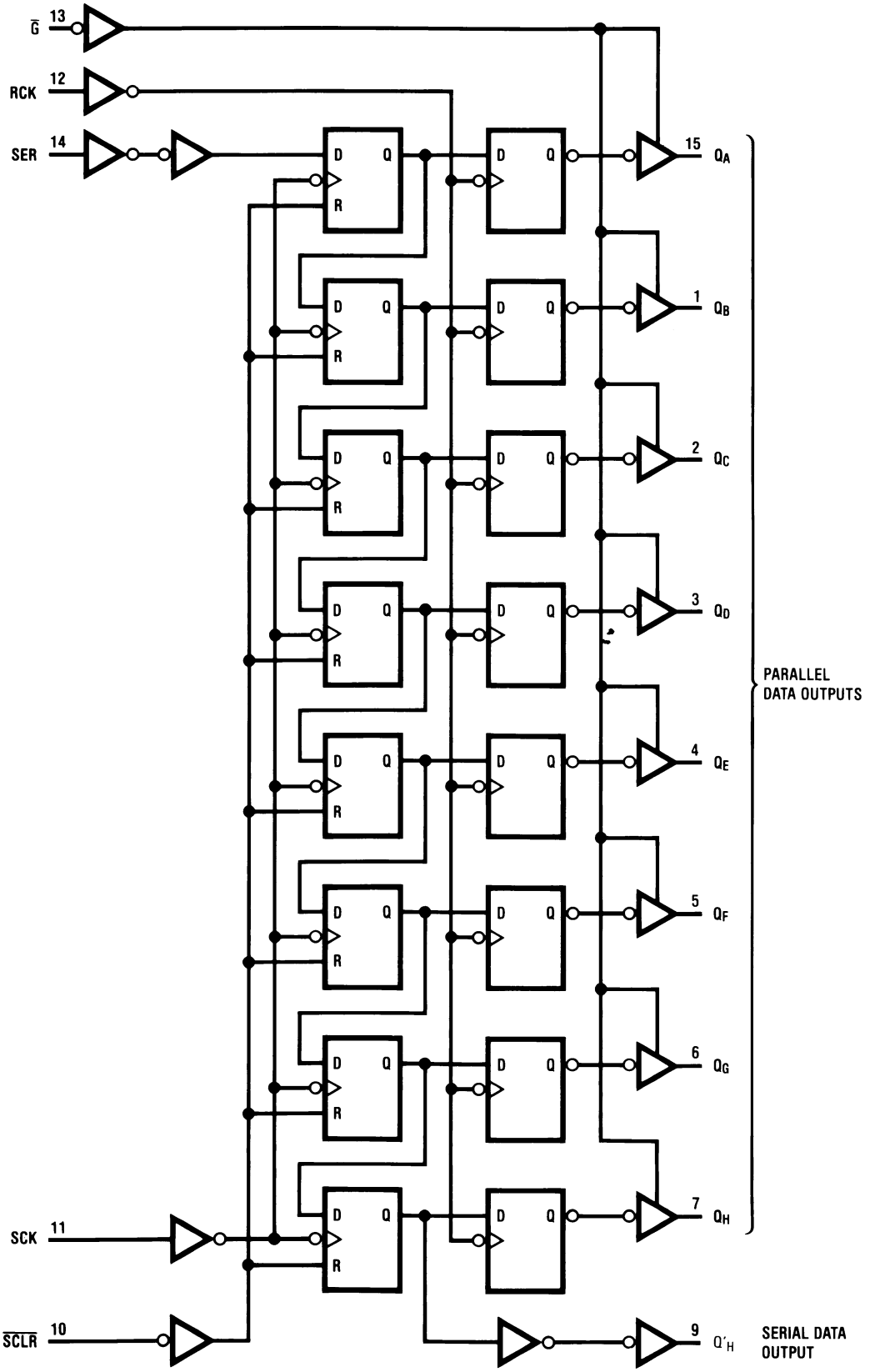
Inputs					Function
SER	RCK	SCK	$\overline{SCLR}$	$\overline{G}$	
X	X	X	X	H	Q_A thru Q_H 3-STATE
X	X	X	X	L	Q_A thru Q_H outputs enabled
X	X	X	L	L	Shift Register cleared: $Q'_H = 0$
L	X	↑	H	L	Shift Register clocked: $Q_N = Q_{n-1}$, Q_0 = SER = L
H	X	↑	H	L	Shift Register clocked: $Q_N = Q_{n-1}$, Q_0 = SER = H
X	↑	X	H	L	Contents of Shift Register transferred to output latches

Timing Diagram



NOTE: ⊠ Implies that the output is in 3-STATE mode.

Logic Diagram (positive logic)



Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	–0.5V to +7.0V
V_{IN}	DC Input Voltage	–0.5V to +7.0V
V_{OUT}	DC Output Voltage	–0.5V to V_{CC} + 0.5V
I_{IK}	Input Diode Current	–20mA
I_{OK}	Output Diode Current	±20mA
I_{OUT}	DC Output Current	±25mA
I_{CC}	DC V_{CC} / GND Current	±75mA
T_{STG}	Storage Temperature	–65°C to +150°C
T_L	Lead Temperature (Soldering, 10 seconds)	260°C

Recommended Operating Conditions(1)

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	2.0V to +5.5V
V_{IN}	Input Voltage	0V to +5.5V
V_{OUT}	Output Voltage	0V to V_{CC}
T_{OPR}	Operating Temperature	–40°C to +85°C
t_r, t_f	Input Rise and Fall Time	
	V_{CC} = 3.3V ±0.3V	0 ~ 100ns/V
	V_{CC} = 5.0V ±0.5V	0 ~ 20ns/V

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions		T_A = 25°C			T_A = –40°C to +85°C		Units
					Min.	Typ.	Max.	Min.	Max.	
V_{IH}	HIGH Level Input Voltage	2.0			1.50			1.50		V
		3.0 – 5.5			0.7 x V_{CC}			0.7 x V_{CC}		
V_{IL}	LOW Level Input Voltage	2.0					0.50		0.50	V
		3.0 – 5.5					0.3 x V_{CC}		0.3 x V_{CC}	
V_{OH}	HIGH Level Output Voltage	2.0	V_{IN} = V_{IH} or V_{IL}	I_{OH} = –50µA	1.9	2.0		1.9		V
		3.0			2.9	3.0		2.9		
		4.5			4.4	4.5		4.4		
		3.0		I_{OH} = –4mA	2.58			2.48		
		4.5		I_{OH} = –8mA	3.94			3.80		
V_{OL}	LOW Level Output Voltage	2.0	V_{IN} = V_{IH} or V_{IL}	I_{OL} = 50µA		0.0	0.1		0.1	V
		3.0				0.0	0.1		0.1	
		4.5				0.0	0.1		0.1	
		3.0		I_{OL} = 4mA			0.36		0.44	
		4.5		I_{OL} = 8mA			0.36		0.44	
I_{OZ}	3-STATE Output Off-State Current	5.5	V_{IN} = V_{CC} or GND, V_{OUT} = V_{CC} or GND, $V_{IN}\overline{G}$ = V_{IH} or V_{IL}				±0.25		±2.5	µA
I_{IN}	Input Leakage Current	0 – 5.5	V_{IN} = 5.5V or GND				±0.1		±1.0	µA
I_{CC}	Quiescent Supply Current	5.5	V_{IN} = V_{CC} or GND				4.0		40.0	µA

Noise Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	T_A = 25°C		Units
				Typ.	Limits	
V_{OLP}(2)	Quiet Output Maximum Dynamic V_{OL}	5.0	C_L = 50pF	0.9	1.2	V
V_{OLV}(2)	Quiet Output Minimum Dynamic V_{OL}	5.0	C_L = 50pF	–0.9	–1.2	V
V_{IHD}(2)	Minimum HIGH Level Dynamic Input Voltage	5.0	C_L = 50pF		3.5	V
V_{ILD}(2)	Maximum LOW Level Dynamic Input Voltage	5.0	C_L = 50pF		1.5	V

Note:

2. Parameter guaranteed by design.

AC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions		T_A = +25°C			T_A = –40°C to +85°C		Units
					Min.	Typ.	Max.	Min.	Max.	
t_{PLH}, t_{PHL}	Propagation Delay Time, RCK to Q_A–Q_H	3.3 ± 0.3		C_L = 15pF		7.7	11.9	1.0	13.5	ns
				C_L = 50pF		10.2	15.4	1.0	17.0	
		5.0 ± 0.5		C_L = 15pF		5.4	7.4	1.0	8.5	ns
				C_L = 50pF		6.9	9.4	1.0	10.5	
t_{PLH}, t_{PHL}	Propagation Delay Time, SCK–Q'H	3.3 ± 0.3		C_L = 15pF		8.8	13.0	1.0	15.0	ns
				C_L = 50pF		11.3	16.5	1.0	18.5	
		5.0 ± 0.5		C_L = 15pF		6.2	8.2	1.0	9.4	ns
				C_L = 50pF		7.7	10.2	1.0	11.4	
t_{PHL}	Propagation Delay Time, $\overline{SCLR}$ –Q'H	3.3 ± 0.3		C_L = 15pF		8.4	12.8	1.0	13.7	ns
				C_L = 50pF		10.9	16.3	1.0	17.2	
		5.0 ± 0.5		C_L = 15pF		5.9	8.0	1.0	9.1	ns
				C_L = 50pF		7.4	10.0	1.0	11.1	
t_{PZL}, t_{PZH}	Output Enable Time, $\overline{G}$ to Q_A–Q_H	3.3 ± 0.3	R_L = 1kΩ	C_L = 15pF		7.5	11.5	1.0	13.5	ns
				C_L = 50pF		9.0	15.0	1.0	17.0	
		5.0 ± 0.5		C_L = 15pF		4.8	8.6	1.0	10.0	ns
				C_L = 50pF		8.3	10.6	1.0	12.0	
t_{PLZ}, t_{PHZ}	Output Disable Time, $\overline{G}$ to Q_A–Q_H	3.3 ± 0.3	R_L = 1kΩ	C_L = 50pF		12.1	15.7	1.0	16.2	ns
		5.0 ± 0.5		C_L = 50pF		7.6	10.3	1.0	11.0	
f_{MAX}	Maximum Clock Frequency	3.3 ± 0.3		C_L = 15pF	80	150		70		MHz
				C_L = 50pF	55	130		50		
		5.0 ± 0.5		C_L = 15pF	135	185		115		MHz
				C_L = 50pF	95	155		85		
t_{OSLH}, t_{OSHL}	Output to Output Skew	3.3 ± 0.3	(3)	C_L = 50pF			1.5		1.5	ns
		5.0 ± 0.5		C_L = 50pF			1.0		1.0	
C_{IN}	Input Capacitance		V_{CC} = Open			5.0	10		10	pF
C_{OUT}	Output Capacitance		V_{CC} = 5.0V			6.0				pF
C_{PD}	Power Dissipation Capacitance		(4)			87				pF

Notes:

3. Parameter guaranteed by design. $t_{OSLH} = |t_{PLH}\ max - t_{PLH}\ min|$; $t_{OSHL} = |t_{PHL}\ max - t_{PHL}\ min|$

4. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:
   $I_{CC}\ (Opr.) = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}$

AC Operating Requirements

Symbol	Parameter	V_{CC} (V)	$T_A = 25°C$		$T_A = -40°C$ to $+85°C$	Units
			Typ.	Guaranteed Minimum		
t_S	Minimum Setup Time (SER–SCK)	3.3 ± 0.3		3.5	3.5	ns
		5.0 ± 0.5		3.0	3.0	
t_S	Minimum Setup Time (SCK–RCK)	3.3 ± 0.3		8.0	8.5	ns
		5.0 ± 0.5		5.0	5.0	
t_S	Minimum Setup Time ($\overline{SCLR}$–RCK)	3.3 ± 0.3		8.0	9.0	ns
		5.0 ± 0.5		5.0	5.0	
t_H	Minimum Hold Time (SER–SCK)	3.3 ± 0.3		1.5	1.5	ns
		5.0 ± 0.5		2.0	2.0	
t_H	Minimum Hold Time (SCK–RCK)	3.3 ± 0.3		0.0	0.0	ns
		5.0 ± 0.5		0.0	0.0	
t_H	Minimum Hold Time ($\overline{SCLR}$–RCK)	3.3 ± 0.3		0.0	0.0	ns
		5.0 ± 0.5		0.0	0.0	
$t_{W(L)}$	Minimum Pulse Width ($\overline{SCLR}$)	3.3 ± 0.3		5.0	5.0	ns
		5.0 ± 0.5		5.0	5.0	
$t_{W(L)}$, $t_{W(H)}$	Minimum Pulse Width (SCK)	3.3 ± 0.3		5.0	5.0	ns
		5.0 ± 0.5		5.0	5.0	
$t_{W(L)}$, $t_W(H)$	Minimum Pulse Width (RCK)	3.3 ± 0.3		5.0	5.0	ns
		5.0 ± 0.5		5.0	5.0	
t_{rem}	Minimum Removal Time ($\overline{SCLR}$–SCK)	3.3 ± 0.3		3.0	3.0	ns
		5.0 ± 0.5		2.5	2.5	

Physical Dimensions

Dimensions are in millimeters unless otherwise noted.

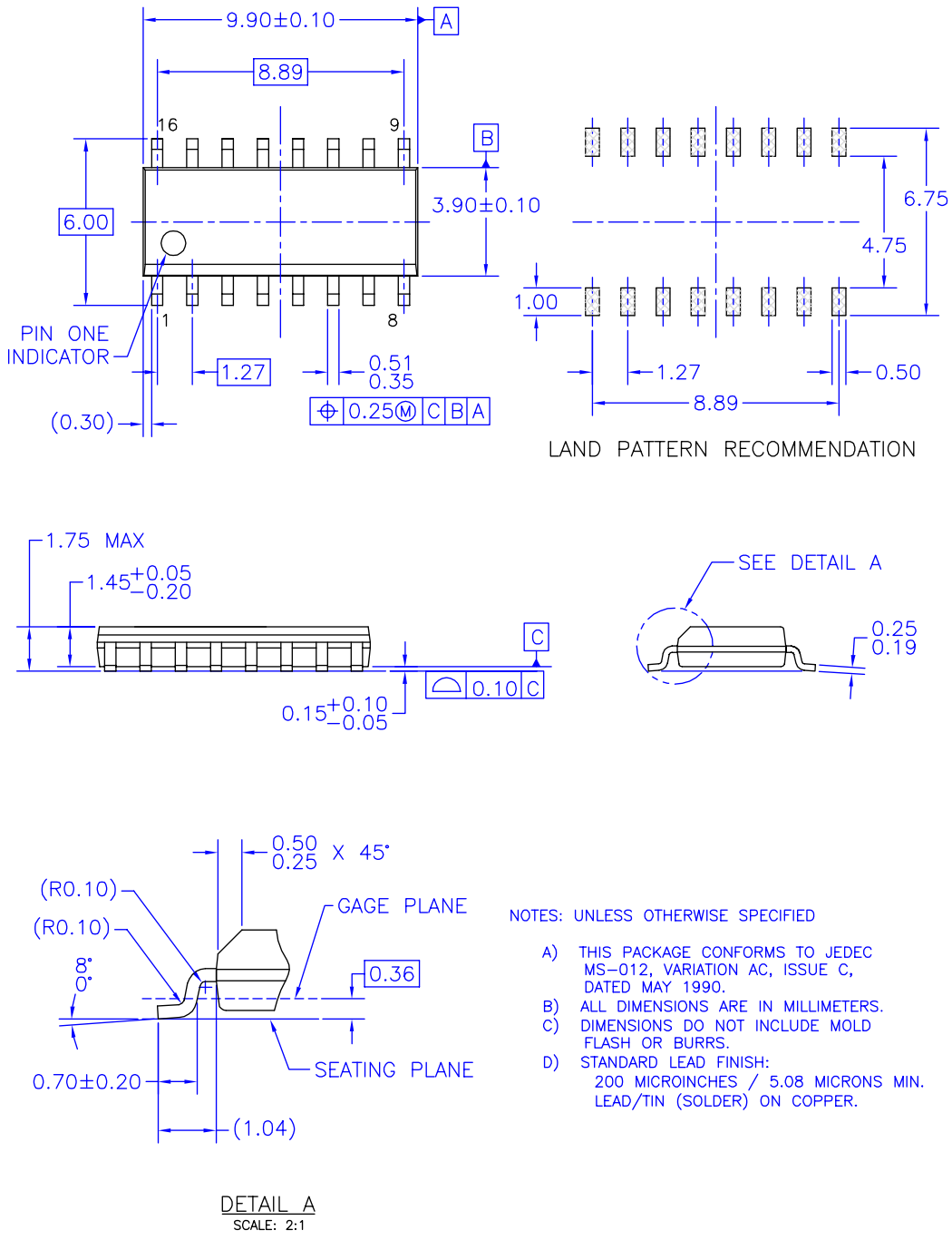


Figure 1. 16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M16A

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.

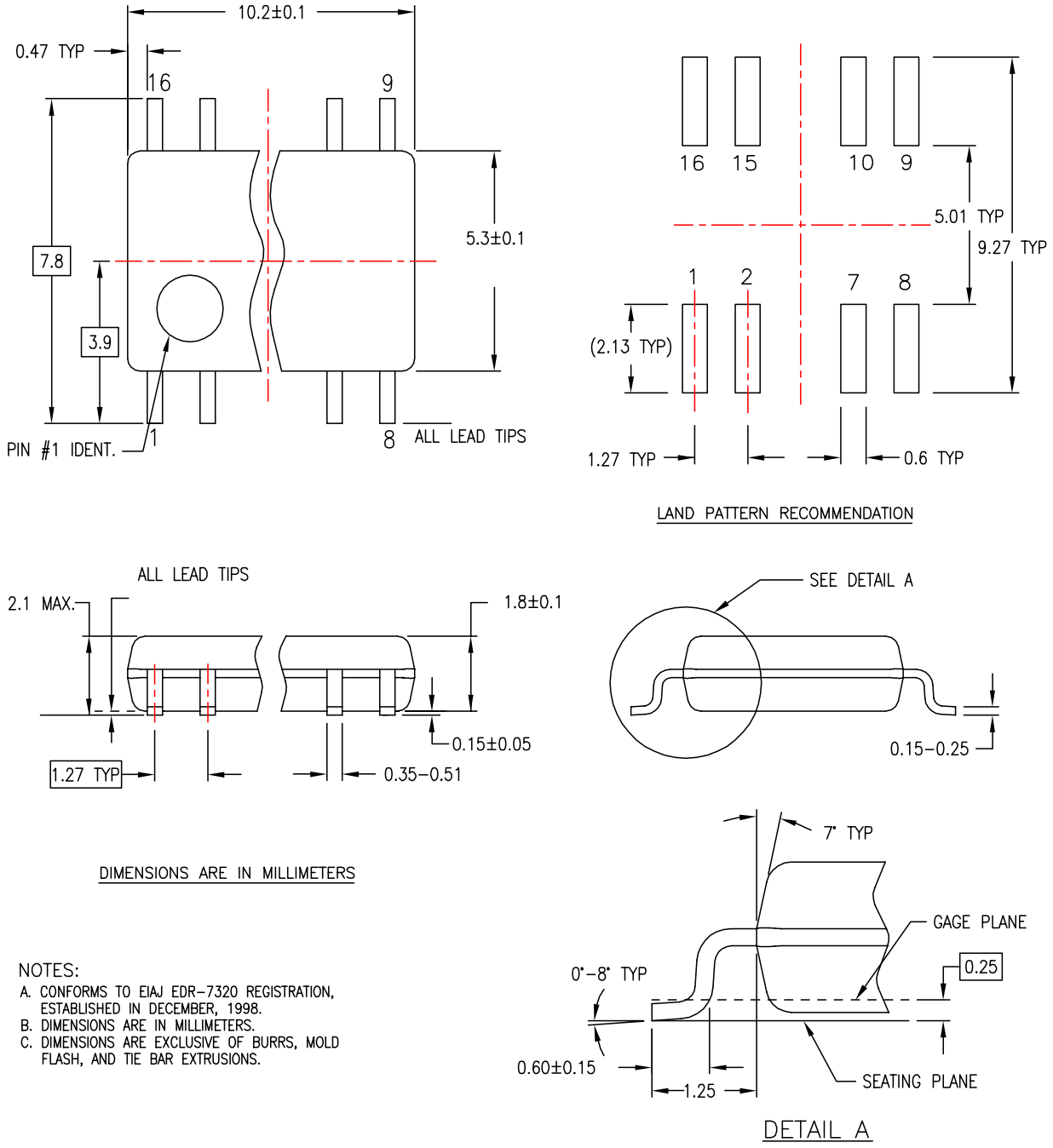
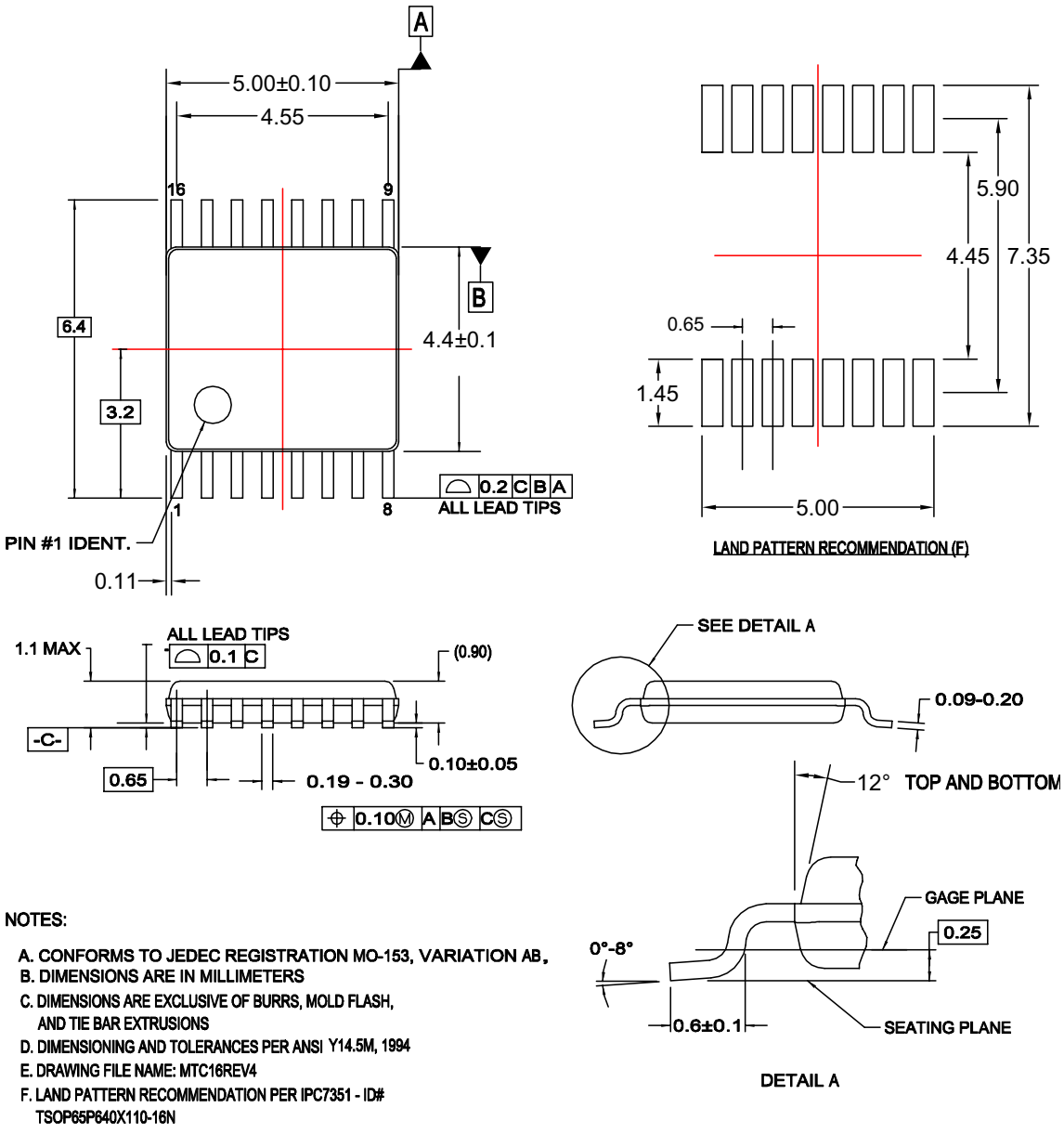


Figure 2. 16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB.
B. DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1994
E. DRAWING FILE NAME: MTC16REV4
F. LAND PATTERN RECOMMENDATION PER IPC7351 - ID# TSOP65P640X110-16N

MTC16rev4

Figure 3. 16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC16

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SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SyncFET™
TCM™
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